ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH ROUTED CIRCUIT LEAD ARRAY AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: providing a terminal having a top with a depression; applying a dielectric material in the depression, the dielectric material having a gap formed therein and exposing a portion of the top therefrom; forming a trace within the gap and in direct contact with the top, the trace extending laterally over an upper surface of the dielectric material; and connecting an integrated circuit to the terminal through the trace.
(Fig. 2)